



S1000

(ANSI:FR-4)Low Z-CTE

特点

- 无铅兼容FR-4板材。
- Tg(DSC)155℃,UV Blocking 和 AOI兼容。
- 优良的耐热性。
- 比普通FR-4降低约30~35%的Z轴热膨胀系数。
- 优良的通孔可靠性。
- 优异的耐CAF性和Q1000性能。
- 低吸水性。

FEATURES

- Lead-free compatible FR-4 Laminate.
- Tg(DSC)155℃,UV Blocking/ AOI compatible.
- Excellent thermal reliability.
- Z-CTE 30~35% less than conventional FR-4.
- Excellent T/H reliability.
- Excellent anti-CAF and Q1000 performance.
- Low water absorption.

应用领域

电脑、仪器仪表、摄像机、通讯设备、汽车、电子游戏机等。

APPLICATIONS

Computer, Instrumentation, VCR, communication equipment, automotive electronics, electronic game machine, and etc.

GENERAL PROPERTIES

Test Item	Treatment Condition	Unit	Property Data		
			SPEC	Typical Value	
Tg	DSC	℃	≥150	155	
Flammability	C-48/23/50	-	V-0	V-0	
	E-24/125				
Volume Resistivity	After moisture resistance	MΩ-cm	≥10 ⁶	7.4×10 ⁸	
	E-24/125		≥10 ³	5.6×10 ⁷	
Surface Resistivity	After moisture resistance	MΩ	≥10 ⁴	7.6×10 ⁷	
	E-24/125		≥10 ³	2.8×10 ⁷	
Arc Resistance	D-48/50+D-0.5/23	S	≥60	147	
Dielectric Breakdown	D-48/50+D-0.5/23	KV	≥40	45	
Dielectric Constant (1MHz)	C-24/23/50	-	≤5.4	4.9	
Dissipation Factor (1MHz)	C-24/23/50	-	≤0.035	0.011	
Thermal Stress	Unetched	288℃,solder dip	-	>10s	100s
	Etched			No delamination	No delamination
Peel Strength	1oz Cu. Foil	288℃,10s	N/mm	≥1.05	1.4
		125℃		≥0.70	1.2
Flexural Strength	LW	A	MPa	≥415	540
	CW			≥345	450
Water Absorption	D-24/23	%	≤0.5	0.09	
CTE	Before Tg	TMA	PPM/℃	≤60	43
	After Tg	TMA	PPM/℃	≤300	245
Z-axis	50~260℃	TMA	%	≤3.5	3.0
Td	10℃/min,N ₂	℃	≥325	335	
T288	TMA	min	≥5	10	
T260	TMA	min	≥30	60	
CTI	IEC60112	V	175~250(grade3)	200	

Remarks: All the data listed above can meet IPC-4101/99 requirement.
Specimen Thickness:1.6mm

Explanations: C = Humidity conditioning;
D = Immersion conditioning in distilled water;
E = Temperature conditioning.

The figures following the letter symbols indicate with the first digit the duration of the preconditioning in hours, with the second digit the preconditioning temperature in ℃ and with the third digit the relative humidity.

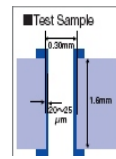
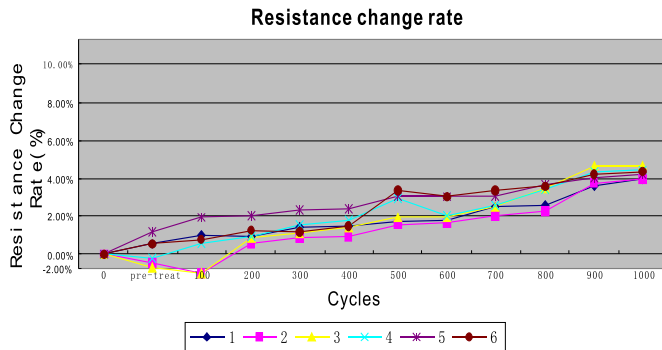


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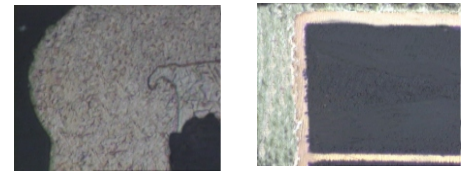
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Thermal Change Test - Q1000

- A) Pre-Treatment:
125 °C/ 2hour in the oven.
- B) Thermal shock condition:
-40°C(30min)~+126°C(30min),transfer time<2min.

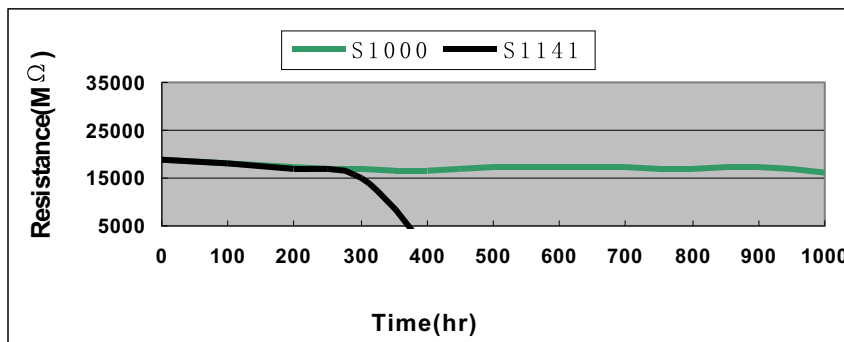


Micro-section after Q1000



X200 micro-section X50 micro-section

Anti-CAF Test



Specimen: Pitch=0.7mm, ϕ =0.3mm,DC100V/40°C/92%RH

PCT(High Pressure Cooker Test)

PCT (E-121°C/105KPa)	Solder Dipping@288°C/10 s	
	Normal FR-4	S1000
30 min	OK	OK
60 min	OK	OK
120 min	NG	OK

Specimen: 1.6mm(uncladding) 100mm*100mm

PURCHASING INFORMATION

Thickness	Copper foil	Standard Size	
0.05mm to 3.2mm	12 μ m to 105 μ m	1,020×1,220mm (40" ×48")	915×1,220mm (36" ×48")
		1,070×1,220mm (42" ×48")	

❖ Other sheet size and thickness could be available upon request.



S1000B PREPREG

(ANSI:FR-4) Bonding Prepreg For S1000

特点

- 高Tg 155℃,有优异的耐热性。
- 低的Z轴膨胀系数。
- 优良的耐化学性能。
- 良好的粘合性能与PCB可加工性能。
- UV Blocking与AOI兼容。

FEATURES

- Tg 155°C and good thermal resistance resistance.
- Low Z- CTE.
- Excellent chemical resistance.
- Excellent adhesion property and PCB processability.
- UV Blocking /AOI compatible.

PREPREG PARAMETERS

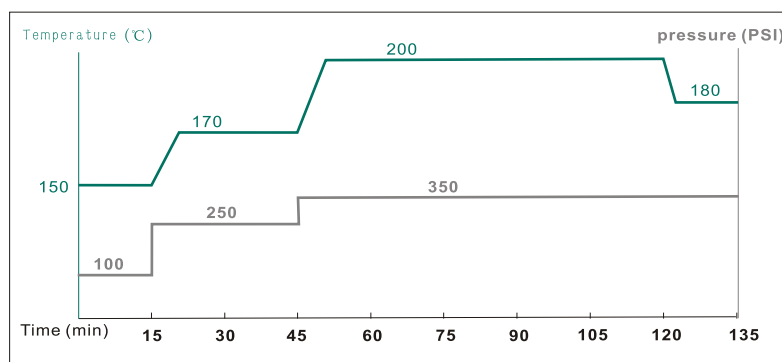
Designation	Glass fabric type	Performance	Gel time (sec)	Resin content (%)	Resin flow (%)	Cured Thickness (μm)	Standard Size (roll type)
S1000B	106	Low Z-CTE	85±20	73±3	37±5	48±10	1,260mm×114.3m (125yards)
	106LD			73±3	37±5	48±10	
	1080			67±3	34±5	76±10	
	1080LD			67±3	33±5	76±10	
	2112			60±3	30±5	90±15	
	2113			59±3	26±5	100±15	
	2313			58±3	26±5	100±15	
	3313			58±3	26±5	100±15	
	2116			55±3	26±5	120±15	
	2165			55±3	26±5	140±15	
	1500			48±3	22±5	160±15	
	7628			46±3	21±5	195±20	

Type, Resin content and Size Could be Available Upon Request

Prepreg Test Method

- Resin content, Resin Flow, Gel Time: IPC-TM-650

HOT PRESSING CYCLE



Heat-up rate: 1.5~2.5°C/min (80~140°C)

Curing time: >45min (180~190°C)

STORAGE CONDITION

- For short term storage, keep in 20°C, 50% RH within 3 months.
- For long term storage, keep in 5°C within 6 months, normalize in room temperature for at least 4h before using.
- Beware of moisture, always keep wrapped in damp-proof material. Were kept in normal condition, prepreg might absorb moisture and its bonding strength would be weakened.
- Avoid UV-rays and strong light.